

FLIP CHIP IN LEADED MOLDED PACKAGE WITH TWO DIES

ABSTRACT OF THE DISCLOSURE

A chip device including two stacked dies. The chip device includes a
5 leadframe that includes a plurality of leads. A first die is coupled to a first side of the
leadframe with solder and a second die is coupled to a second side of the leadframe with
solder. A molded body surrounds at least a portion of the leadframe and the dies.

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